

# UT7C138/139 4Kx8/9 Radiation-Hardened Dual-Port Static RAM with Busy Flag

Preliminary Data Sheet

May 1996

## FEATURES

- ❑ 45ns and 55ns maximum address access time
- ❑ Asynchronous operation for compatibility with industry-standard 4K x 8/9 dual-port static RAM
- ❑ CMOS compatible inputs, TTL/CMOS compatible output levels
- ❑ Three-state bidirectional data bus
- ❑ Low operating and standby current
- ❑ Radiation-hardened process and design; total dose irradiation testing to MIL-STD-883 Method 1019
  - Total-dose: 1.0E6 rads(Si)
  - Memory Cell LET threshold: 65 MeV-cm<sup>2</sup>/mg
  - Latchup immune (LET >100 MeV-cm<sup>2</sup>/mg)
- ❑ QML Q and QML V compliant part
- ❑ Packaging options:
  - 68-lead Flatpack
  - 68-pin PGA
- ❑ 5-volt operation
- ❑ Standard Microcircuit Drawing 5962-96845

## INTRODUCTION

The UT7C138 and UT7C139 are high-speed radiation-hardened CMOS 4K x 8 and 4K x 9 dual-port static RAMs. Arbitration schemes are included on the UT7C138/139 to handle situations when multiple processors access the same memory location. Two ports provide independent, asynchronous access for reads and writes to any location in memory. The UT7C138/139 can be utilized as a stand-alone 32/36-Kbit dual-port static RAM or multiple devices can be combined in order to function as a 16/18-bit or wider master/slave dual-port static RAM. For applications that require depth expansion, the BUSY pin is open-collector allowing for wired OR circuit configuration. An M/S pin is provided for implementing 16/18-bit or wider memory applications without the need for separate master and slave devices or additional discrete logic. Application areas include interprocessor/multiprocessor designs, communications, and status buffering.

Each port has independent control pins: chip enable ( $\overline{CE}$ ), read or write enable (R/W), and output enable ( $\overline{OE}$ ). BUSY signals that the port is trying to access the same location currently being accessed by the other port.

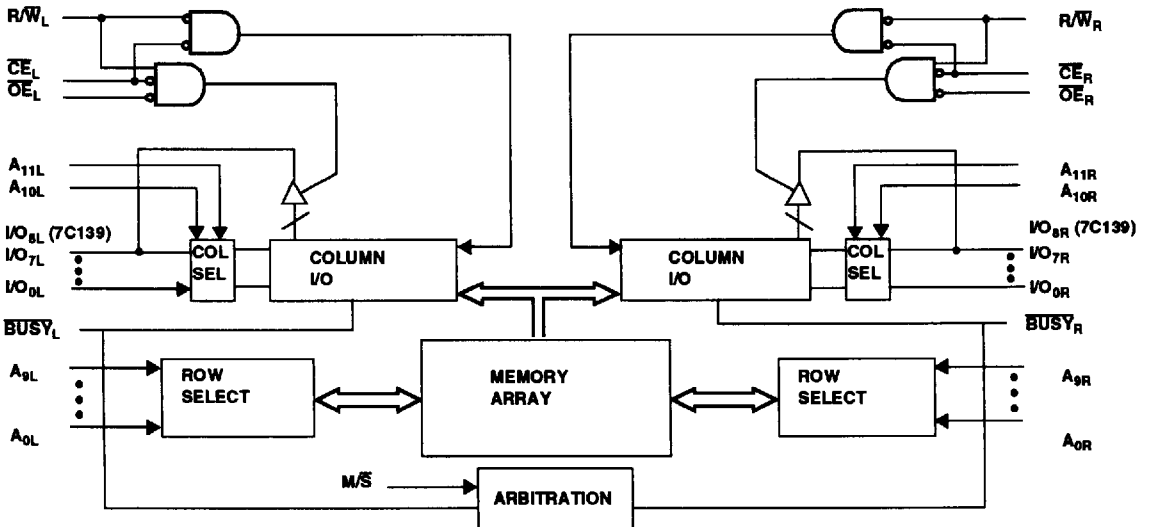
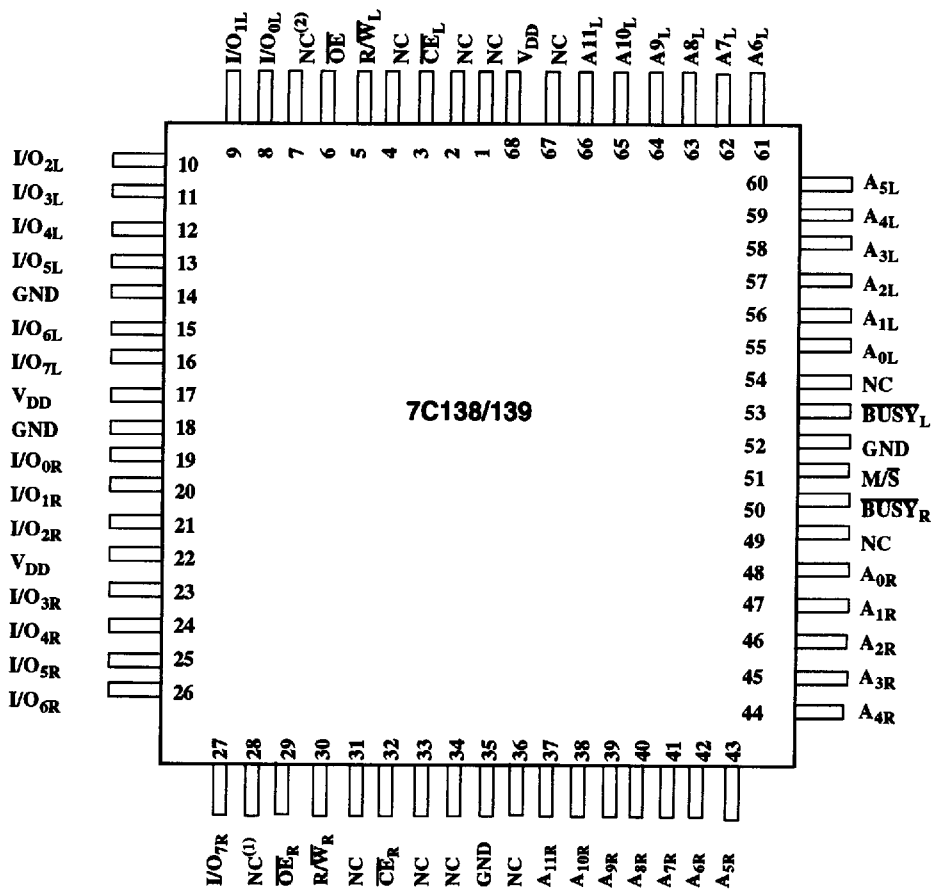


Figure 1. Logic Block Diagram



**Figure 2a. DPRAM Pinout (68-Flatpack)**  
(top view)

- Notes:**
1. I/O<sub>8R</sub> on the 7C139
  2. I/O<sub>8L</sub> on the 7C139

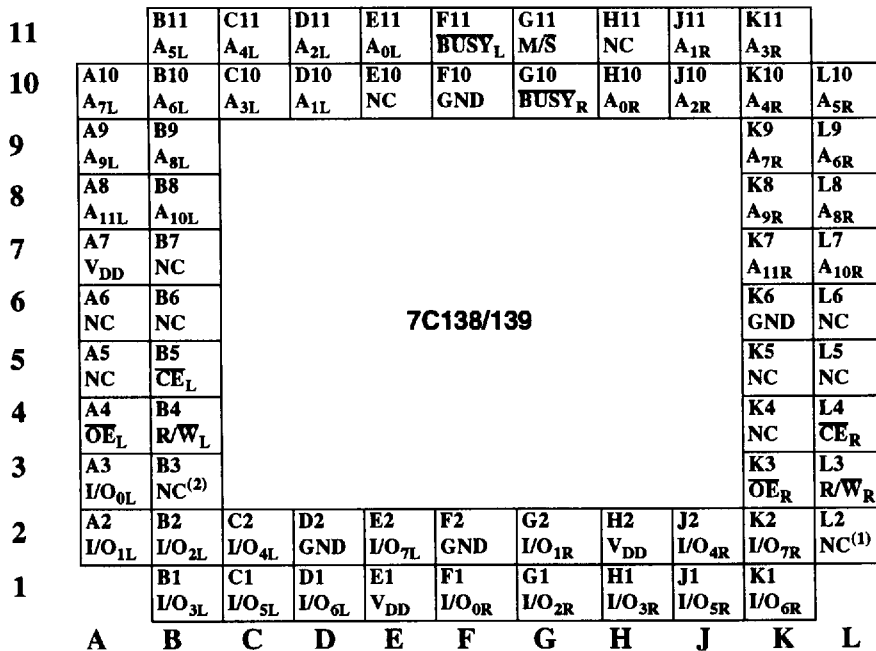


Figure 2b: DPRAM Pinout (68 PGA)  
(top view)

Notes:

1. I/O<sub>8R</sub> on the 7C139
2. I/O<sub>8L</sub> on the 7C139

PIN NAMES

LEFT PORT	RIGHT PORT	DESCRIPTION
I/O <sub>0L-7L</sub> (8L)	I/O <sub>0R-7R</sub> (8R)	Data Bus Input/Output
A <sub>0L-11L</sub>	A <sub>0R-11R</sub>	Address Lines
CE <sub>L</sub>	CE <sub>R</sub>	Chip Enable
OE <sub>L</sub>	OE <sub>R</sub>	Output Enable
R/W <sub>L</sub>	R/W <sub>R</sub>	Read/Write Enable
BUSY <sub>L</sub>	BUSY <sub>R</sub>	Busy Flag Input/Output
M/S		Master or Slave Select
V <sub>DD</sub>		Power
GND		Ground

The UT7C138/139 consists of an array of 4K words of 8 or 9 bits of dual-port SRAM cells, I/O and address lines, and control signals (**CE**, **OE**, **R/W**). These control pins permit independent access for reads or writes to any location in memory. To handle simultaneous writes/reads to the same location, a **BUSY** pin is provided on each port. With the **M/S** pin, the UT7C138/139 can function as a master (**BUSY** pins are outputs) or as a slave (**BUSY** pins are inputs). Each port is provided with its own output enable control (**OE**), which allows data to be read from the device.

### WRITE CYCLE

A combination of **R/W** less than  $V_{IL}$  (max), **CE** less than  $V_{IL}$  (max), defines a write cycle. The state of **OE** is a "don't care" for a write cycle. The outputs are placed in the high-impedance state when either **OE** is greater than  $V_{IH}$  (min), or when **R/W** is less than  $V_{IL}$  (max).

### WRITE OPERATION

Write Cycle 1, the Write Enable-controlled Access shown in figure 4a, is defined by a write terminated by **R/W** going high with **CE** active. The write pulse width is defined by  $t_{PWE}$  when the write is initiated by **R/W**, and by  $t_{SCE}$  when the write is initiated by **CE** going active. Unless the outputs have been previously placed in the high-impedance state by **OE**, the user must wait  $t_{HZOE}$  before applying data to the eight/nine bidirectional pins I/O(7:0/8:0) to avoid bus contention.

Write Cycle 2, the Chip Enable-controlled Access shown in figure 4b, is defined by a write terminated by **CE** going inactive. The write pulse width is defined by  $t_{PWE}$  when the write is initiated by **R/W**, and by  $t_{SCE}$  when the write is initiated by **CE** going active. For the **R/W** initiated write, unless the outputs have been previously placed in the high-impedance state by **OE**, the user must wait  $t_{HZWE}$  before applying data to the eight/nine bidirectional pins I/O(7:0/8:0) to avoid bus contention.

If a location is being written by one port and the opposite port attempts to read that location, a port-to-port flow through delay must be met before the data is read on the output. Data will be valid on the port wishing to read the location  $t_{BZA} + t_{BDD}$  after the data is written on the other port (see figure 5a).

### READ OPERATION

When reading the device, the user must assert both the **OE** and **CE** pins. Data will be available  $t_{ACE}$  after **CE** or  $t_{DOE}$  after **OE** is asserted (see figures 3a and 3b).

### MASTER/SLAVE

A **M/S** pin is provided in order to expand the word width by configuring the device as either a master or a slave. The **BUSY** output of the master is connected to the **BUSY** input of the slave. Writing of slave devices must be delayed until after the **BUSY** input has settled. Otherwise, the slave chip may begin a write cycle during a contention situation. When presented as a HIGH

input, the **M/S** pin allows the device to be used as a master and, therefore, the **BUSY** line is an output. **BUSY** can then be used to send the arbitration outcome to a slave. When presented as a LOW input, the **M/S** pin allows the device to be used as a slave, and, therefore, the **BUSY** pin is an input.

Table 1. Non-Contending Read/Write

INPUTS			OUTPUTS	
CE	R/W	OE	I/O <sub>0-7</sub>	OPERATION
H	X	X	High Z	Power Down
X	X	H	High Z	I/O Lines Disabled
L	H	L	Data Out	Read
L	L	X	Data In	Write
L	X	X	---	Illegal Condition

### RADIATION HARDNESS

The UT7C138/139 incorporates special design and layout features which allow operation in high-level radiation environments. UPMC has developed special low-temperature processing techniques designed to enhance the total-dose radiation hardness of both the gate oxide and the field oxide while maintaining the circuit density and reliability. For transient radiation hardness and latchup immunity, UPMC builds all radiation-hardened products on epitaxial wafers using an advanced twin-tub CMOS process. In addition, UPMC pays special attention to power and ground distribution during the design phase, minimizing dose-rate upset caused by rail collapse.

Table 2. Radiation Hardness Design Specifications<sup>1</sup>

Total Dose	1.0E6	rads(Si)
LET Threshold	65	MeV-cm <sup>2</sup> /mg
Neutron Fluence <sup>2</sup>	3.0E14	n/cm <sup>2</sup>
Memory Cell Cross Section @ LET = 100MeV-cm <sup>2</sup> /mg	4.3E-7	cm <sup>2</sup>

#### Notes:

1. The DPRAM will not latchup during radiation exposure under recommended operating conditions.
2. Not tested for CMOS technology.

### ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

(Referenced to  $V_{SS}$ )

SYMBOL	PARAMETER	LIMITS
$V_{DD}$	DC supply voltage	-0.5 to 7.0V
$V_{IO}$	Voltage on any pin	-0.5 to ( $V_{DD} + 0.3$ )V
$T_{STG}$	Storage temperature	-65 to +150°C
$P_D$	Maximum power dissipation	2.0W
$T_J$	Maximum junction temperature <sup>2</sup>	+150°C
$\theta_{JC}$	Thermal resistance, junction-to-case <sup>3</sup>	3.3°C/W
$I_I$	DC input current	±10 mA

**Notes:**

1. Stresses outside the listed absolute maximum ratings may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at these or any other conditions beyond limits indicated in the operational sections of this specification is not recommended. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.
2. Maximum junction temperature may be increased to +175°C during burn-in and steady-static life.
3. Test per MIL-STD-883, Method 1012.

### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIMITS
$V_{DD}$	Positive supply voltage	4.5 to 5.5V
$T_C$	Case temperature range	-55 to +125°C
$V_{IN}$	DC input voltage	0V to $V_{DD}$

### DC ELECTRICAL CHARACTERISTICS (Pre/Post-Radiation)\*

( $V_{DD} = 5.0V \pm 10\%$ ;  $-55^{\circ}C < T_C < +125^{\circ}C$ )

SYMBOL	PARAMETER	CONDITION	MIN	MAX	UNIT
$V_{IH}$	High-level input voltage	(CMOS)	$0.7V_{DD}$		V
$V_{IL}$	Low-level input voltage	(CMOS)		$0.3V_{DD}$	V
$V_{OL}$	Low-level output voltage	$I_{OL} = 8mA$ , $V_{DD} = 4.5V$ (TTL)		0.4	V
$V_{OL}$	Low-level output voltage	$I_{OL} = 200\mu A$ , $V_{DD} = 4.5V$ (CMOS)		0.05	V
$V_{OH}$	High-level output voltage	$I_{OH} = -4mA$ , $V_{DD} = 4.5V$ (TTL)	2.4		V
$V_{OH}$	High-level output voltage	$I_{OH} = -200\mu A$ , $V_{DD} = 4.5V$ (CMOS)	4.45		V
$C_{IN}^1$	Input capacitance	$f = 1MHz @ 0V$		25	pF
$C_{IO}^1$	Bidirectional I/O capacitance	$f = 1MHz @ 0V$		25	pF
$I_{IN}$	Input leakage current	$V_{IN} = V_{DD}$ and $V_{SS}$	-10	10	$\mu A$
$I_{OZ}$	Three-state output leakage current	$V_O = V_{DD}$ and $V_{SS}$ $V_{DD} = 5.5V$ $\bar{G} = 5.5V$	-10	10	$\mu A$
$I_{OS}^{2,3}$	Short-circuit output current	$V_{DD} = 5.5V$ , $V_O = V_{DD}$ $V_{DD} = 5.5V$ , $V_O = 0V$	-90	90	mA mA
$I_{DD(OP)}^{4,5}$	Supply current operating (both ports) @ 22.2MHz	CMOS inputs ( $I_{OUT} = 0$ ) $V_{DD} = 5.5V$		300	mA
$I_{DD(OP)}^{4,6}$	Supply current operating (single port) @ 22.2 MHz	CMOS inputs ( $I_{OUT} = 0$ ) $V_{DD} = 5.5V$		150	mA
$I_{DD(OP)}^{4,5}$	Supply current operating (both ports) @ 18.2MHz	CMOS inputs ( $I_{OUT} = 0$ ) $V_{DD} = 5.5V$		275	mA
$I_{DD(OP)}^{4,6}$	Supply current operating (single port) @ 18.2 MHz	CMOS inputs ( $I_{OUT} = 0$ ) $V_{DD} = 5.5V$		138	mA
$I_{DD(SB)}^4$	Supply current standby	CMOS inputs ( $I_{OUT} = 0$ ) $CE = V_{DD} - 0.5$ , $V_{DD} = 5.5V$		1	mA

**Notes:**

\* Post-radiation performance guaranteed at 25°C per MIL-STD-883 Method 1019.

1. Measured only for initial qualification and after process or design changes that could affect input/output capacitance.

2. Supplied as a design limit but not guaranteed or tested.

3. Not more than one output may be shorted at a time for maximum duration of one second.

4.  $V_{IH} = 5.5V$ ,  $V_{IL} = 0V$ .

5.  $I_{DD} (OP)$  derates at 6.4mA/MHz.

6.  $I_{DD} (OP)$  derates at 3.4mA/MHz.

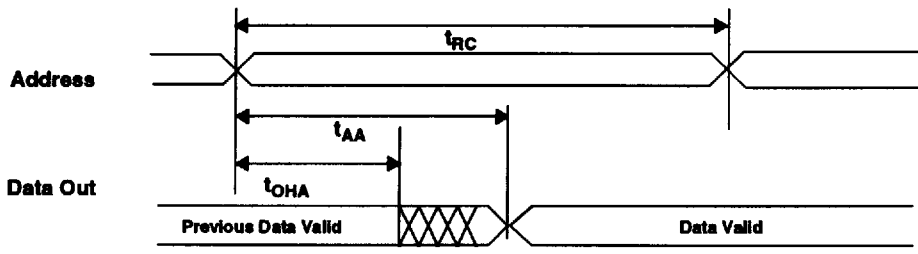
### AC CHARACTERISTICS READ CYCLE <sup>1,2</sup>

( $V_{DD} = 5.0V \pm 10\%$ )

SYMBOL	PARAMETER	7C138 - 45 7C139 - 45		7C138 - 55 7C139 - 55		UNIT
		MIN	MAX	MIN	MAX	
$t_{RC}$	Read cycle time	45		55		ns
$t_{AA}$	Address to data valid <sup>2</sup>		45		55	ns
$t_{OHA}$	Output hold from address change	5		5		ns
$t_{ACE}$	$\overline{CE}$ LOW to data valid <sup>2</sup>		45		55	ns
$t_{DOE}$	$\overline{OE}$ LOW to data valid <sup>2</sup>		20		20	ns
$t_{LZOE}$	$\overline{OE}$ LOW to low Z	0		0		ns
$t_{HZOE}$	$\overline{OE}$ HIGH to high Z		20		20	ns
$t_{LZCE}$	$\overline{CE}$ LOW to low Z	0		0		ns
$t_{HZCE}$	$\overline{CE}$ HIGH to high Z		20		20	ns

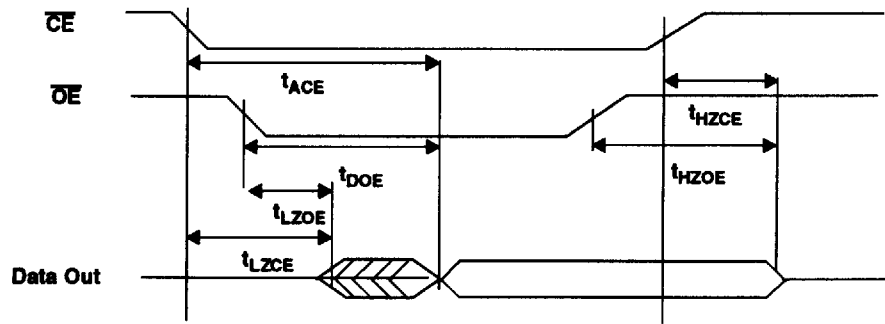
**Notes:**

1. Test conditions assume signal transition time of 5ns or less, turning reference levels of  $V_{DD}/2$ , input pulse levels of 0.5V to  $V_{DD}-0.5V$ , and output loading of the specified  $I_{OL}/I_{OH}$  and 50-pF load capacitance.
2. AC test conditions use  $V_{OH}/V_{OL} = V_{DD}/2 \pm 350mV$ .



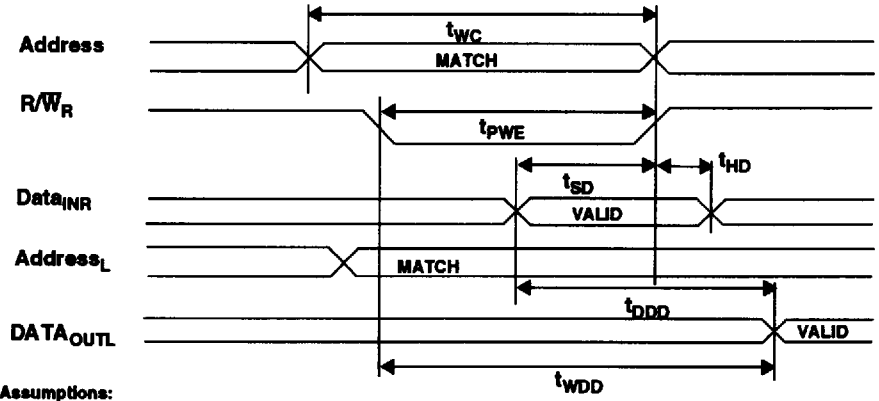
- Assumptions:**
1.  $R/\overline{W}$  is HIGH for read cycle
  2. Device is continuously selected  $\overline{CE}=\text{LOW}$  and  $\overline{OE}=\text{LOW}$

Figure 3a. Read Cycle 1



- Assumptions:**
1. Address valid prior to or coincident with  $\overline{CE}$  transition LOW
  2.  $R/\overline{W}$  is HIGH for read cycle

Figure 3b. Read Cycle 2



- Assumptions:**
1. BUSY = HIGH for the writing port
  2.  $\overline{CE}_L = \overline{CE}_R = \text{LOW}$

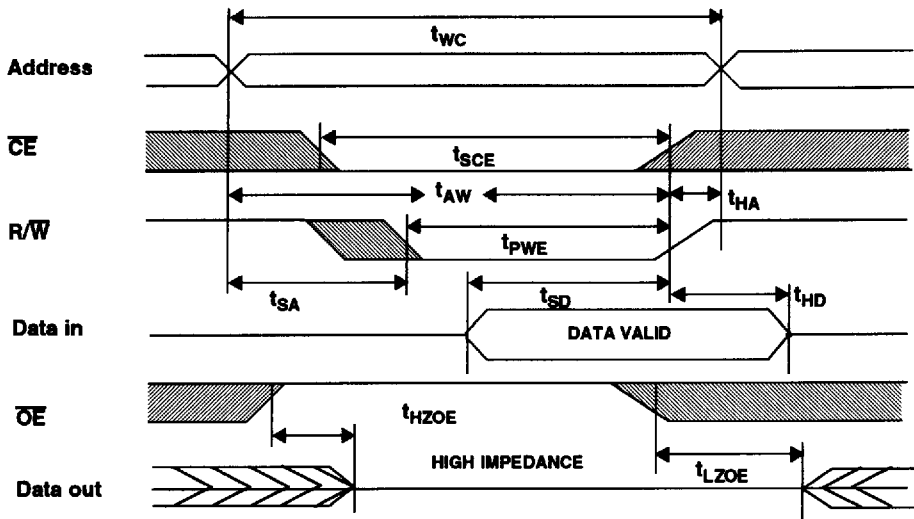
Figure 3c. Read Timing with Port-to-Port Delay

**AC CHARACTERISTICS WRITE CYCLE <sup>1</sup>**  
(V<sub>DD</sub> = 5.0V±10%)

SYMBOL	PARAMETER	7C138 - 45 7C139 - 45		7C138 - 55 7C139 - 55		UNIT
		MIN	MAX	MIN	MAX	
t <sub>WC</sub>	Write cycle time	45		55		ns
t <sub>SCE</sub>	CE LOW to write end	40		50		ns
t <sub>AW</sub>	Address set-up to write end	40		50		ns
t <sub>HA</sub>	Address hold from write end	0		0		ns
t <sub>SA</sub>	Address set-up to write start	0		0		ns
t <sub>PWE</sub>	Write pulse width	40		50		ns
t <sub>SD</sub>	Data set-up to write end	40		50		ns
t <sub>HD</sub>	Data hold from write end	0		0		ns
t <sub>HZWE</sub>	R/W LOW to high Z		20		20	ns
t <sub>LZWE</sub>	R/W HIGH to low Z	0		0		ns
t <sub>WDD</sub>	Write pulse to data delay	95		105		ns
t <sub>DDD</sub>	Write data valid to read data valid	95		105		ns
t <sub>WHWL</sub>	Write disable time	5		5		ns

**Notes:**

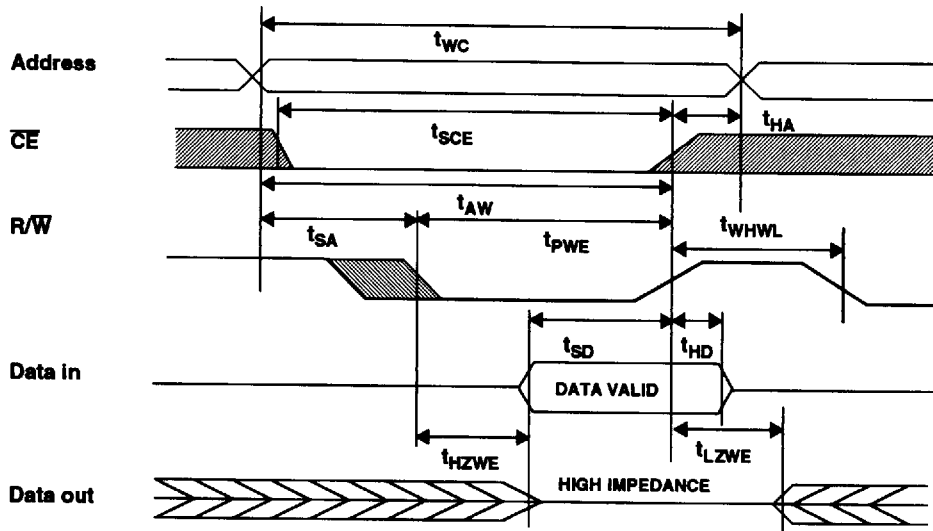
1. For information on part-to-part delay through DPRAM cells from writing port to reading port, refer to Read Tuning with Port-to-Port Delay waveform (see figure 3c).



**Assumptions:**

1. The internal write time of memory is defined by the overlap of  $\overline{CE}$  LOW and  $R/\overline{W}$  LOW. Both signals must be LOW to initiate a write, and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
2. If  $\overline{OE}$  is LOW during a  $R/\overline{W}$  controlled write cycle, the write pulse width must be the larger of  $t_{PWE}$  or  $(t_{HZOE} + t_{SD})$  to allow the I/O drivers to turn off and data to be placed on the bus for the required  $t_{SD}$ . If  $\overline{OE}$  is HIGH during a  $R/\overline{W}$  controlled write cycle (as in this example), this requirement does not apply and the write pulse can be as short as the specified  $t_{PWE}$ .
3.  $R/\overline{W}$  must be HIGH during all address transactions.

Figure 4a. Write Cycle 1:  $\overline{OE}$  Three-States Data I/Os (Either Port)



**Assumptions:**

1. The internal write time of memory is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{R/W}$  LOW. Both signals must be LOW to initialize a write, and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
2.  $\overline{R/W}$  must be HIGH during all address transactions.
3. Data I/O pins enter high impedance even if  $\overline{OE}$  is held LOW during write.

Figure 4b. Write Cycle 2:  $\overline{R/W}$  Three-States Data I/Os (Either Port)

### AC CHARACTERISTICS BUSY CYCLE <sup>1</sup>

( $V_{DD} = 5.0V \pm 10\%$ )

SYMBOL	PARAMETER	7C138 - 45		7C138 - 55		UNIT
		7C139 - 45	7C139 - 55	7C139 - 55	7C139 - 55	
		MIN	MAX	MIN	MAX	
$t_{BLA}$	BUSY LOW from address match		25		30	ns
$t_{BZA}$	$\overline{\text{BUSY}}$ HIGH-Z from address mismatch		25		30	ns
$t_{BLC}$	BUSY LOW from $\overline{\text{CE}}$ LOW		25		30	ns
$t_{BZC}$	BUSY HIGH from $\overline{\text{CE}}$ HIGH		25		30	ns
$t_{PS}^{2,3}$	Port set-up for priority		5		5	ns
$t_{WB}$	R/ $\overline{\text{W}}$ LOW after $\overline{\text{BUSY}}$ LOW		0		0	ns
$t_{WH}$	R/ $\overline{\text{W}}$ HIGH after $\overline{\text{BUSY}}$ HIGH		40		50	ns
$t_{BDD}$	BUSY HIGH to data valid		45		55	ns

**Notes:**

1. Test conditions assume signal transition time of 5ns or less, timing reference levels of  $V_{DD}/2$ , input pulse levels of 0.5V to  $V_{DD}-0.5V$ , and output loading of the specified  $I_{OL}/I_{OH}$  and 50-pF load capacitance.
2. Violation of  $t_{PS}$  (with addresses matching) results in at least one of the two busy output signals asserting, only one port remains busy.
3. When violating  $t_{PS}$ , the busy signal asserts on one port or the other; there is no guarantee on which port the busy signal asserts.

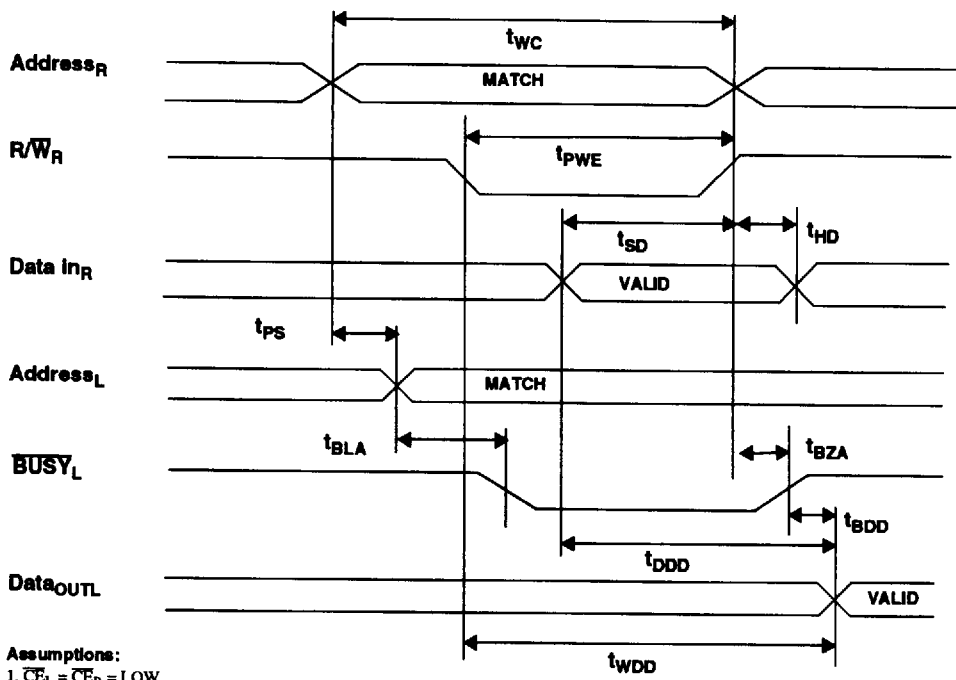


Figure 5a. Read Timing with **BUSY** (M/S=HIGH)

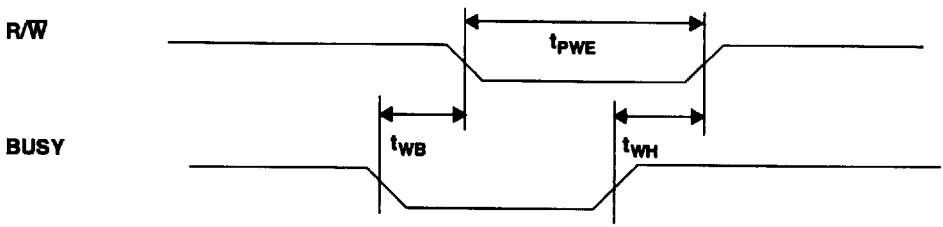
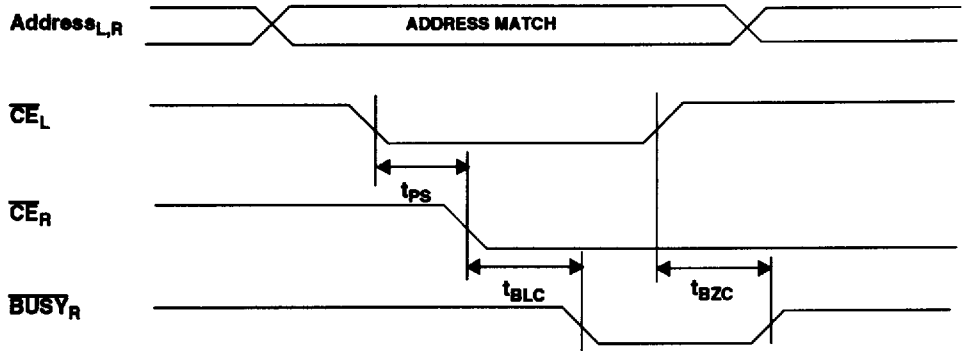
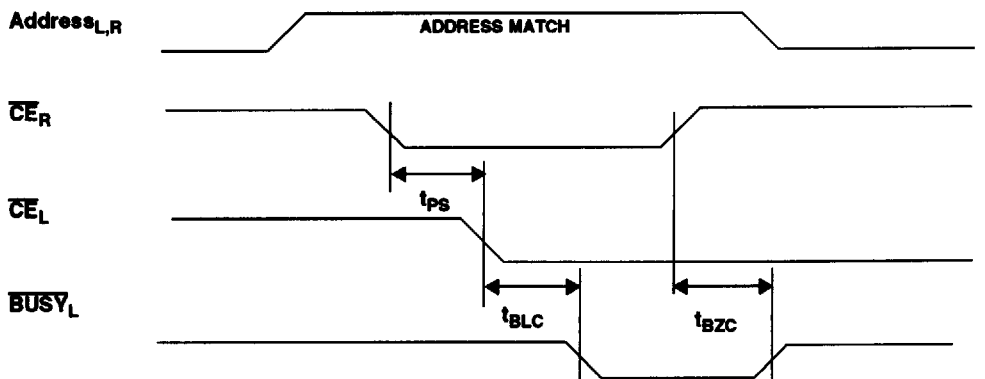


Figure 5b. Write Timing with **BUSY** (M/S=LOW)

**$\overline{CE}_L$  Valid First:**



**$\overline{CE}_R$  Valid First:**

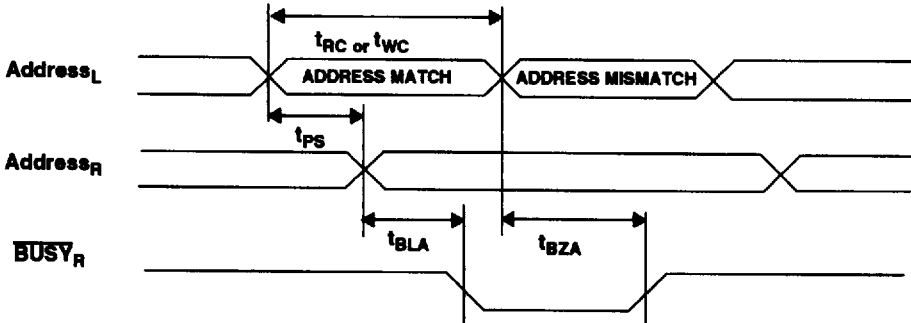


**Assumptions:**

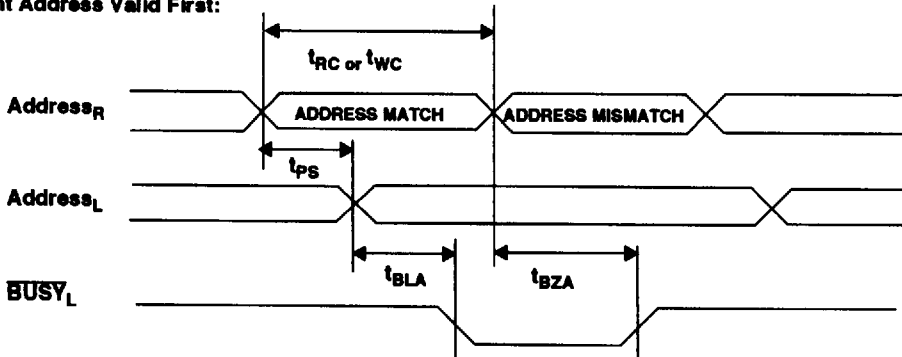
1. If  $t_{ps}$  is violated, the  $BUSY$  signal will be asserted on one side or the other, but there is no guarantee on which side  $BUSY$  will be asserted.

**Figure 5c. BUSY Timing Diagram No. 1 ( $\overline{CE}$  Arbitration)**

**Left Address Valid First:**



**Right Address Valid First:**



**Assumptions:**

1. If  $t_{PS}$  is violated, the **BUSY** signal will be asserted on one side or the other, but there is no guarantee on which side **BUSY** will be asserted.

**Figure 5d. BUSY Timing Diagram No. 2 (Address Arbitration)**

**DATA RETENTION CHARACTERISTICS (Pre-Radiation)**  
 ( $T_C = 25^\circ\text{C}$ )

SYMBOL	PARAMETER	MINIMUM	MAXIMUM $V_{DD} @ 2.5\text{V}$	UNIT
$V_{DR}$	$V_{DD}$ for data retention	2.5	--	V
$I_{DDR}^1$	Data retention current	--	400	$\mu\text{A}$
$t_{EFR}^{1,2}$	Chip deselect to data retention time	0		ns
$t_R^{1,2}$	Operation recovery time	$t_{WC}$ or $t_{RC}$		ns

**Notes:**

1. CE equals  $V_{DR}$ , all other inputs equal  $V_{DR}$  or  $V_{SS}$ .
2. Guaranteed but not tested.

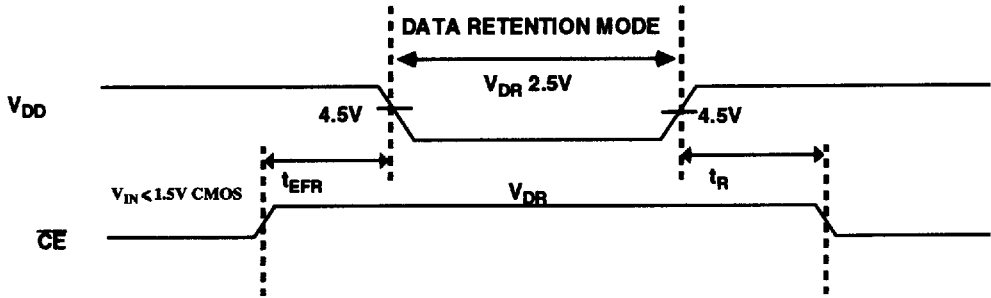
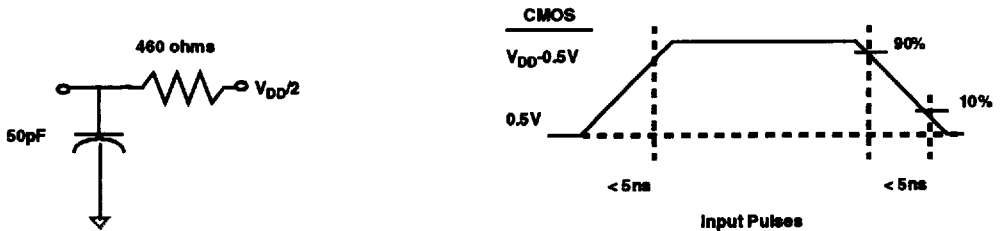


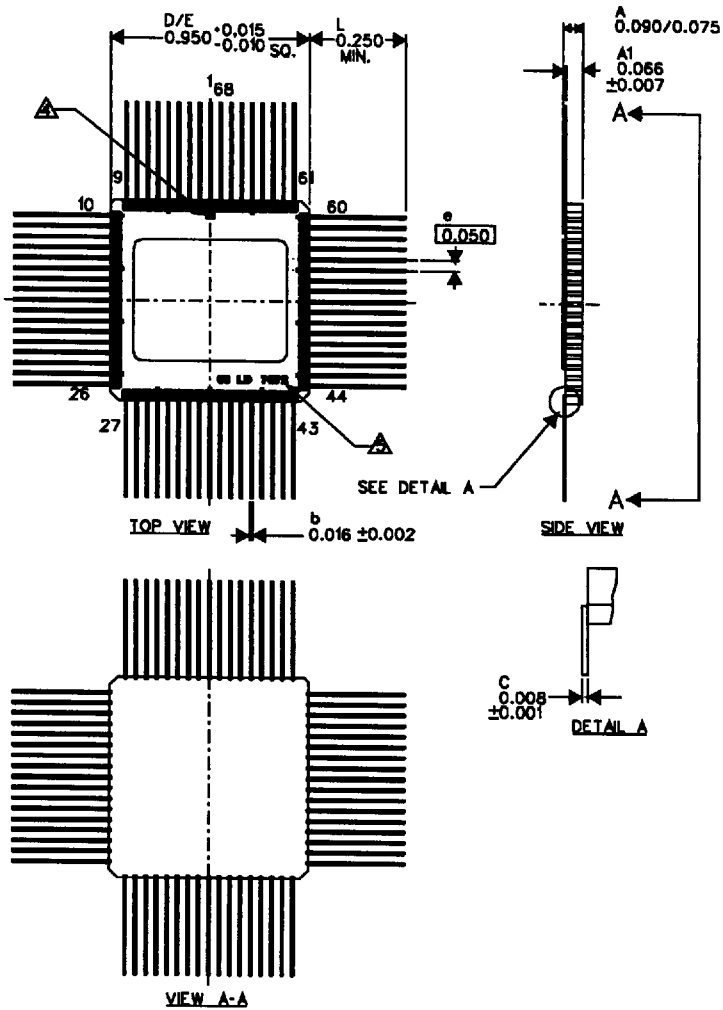
Figure 6. Low  $V_{DD}$  Data Retention Waveform



**Notes:**

1. 50pF including scope probe and test socket.
2. Measurement of data output occurs at the low to high or high to low transition mid-point (CMOS input =  $V_{DD}/2$ ).

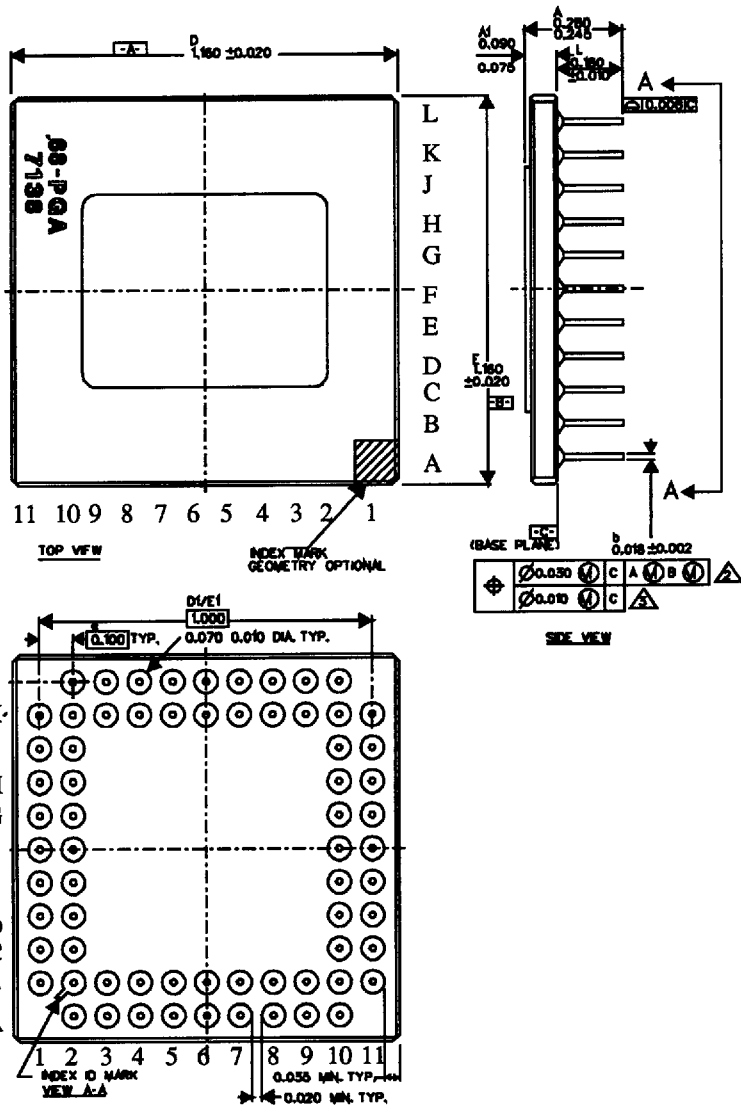
Figure 7. AC Test Loads and Input Waveforms



**Notes:**

1. All package finishes are per MIL-PRF-38535.
2. Letter designations are for cross-reference to MIL-STD-1835.
3. All leads increase max limit by 0.003 measured at the center of the flat, when lead finish A (solder) is applied.
4. ID mark: Configuration is optional.
5. Lettering is not subject to marking criteria.
6. Total weight is approximately 4.5 grams.

Figure 8. 68-lead Flatpack



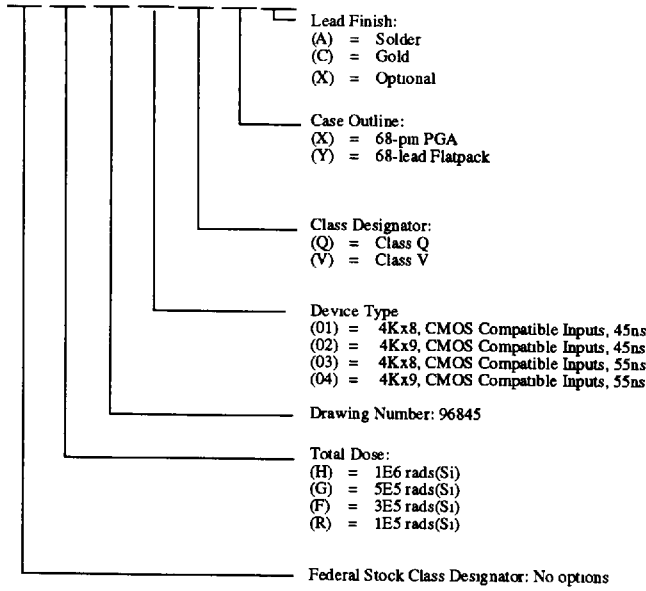
- Notes:**
1. All packages finishes are per MIL-PRF-38535.
  2. True position applies at base plane (Datum C).
  3. True position applies at pin tips.
  4. Letter designations are for cross-reference to MIL-STD-1835.
  5. Total weight is approximately 7.0 grams.

Figure 9. 68-pin PGA

# ORDERING INFORMATION

## UT7C138/UT7C139 Dual-Port SRAM: SMD

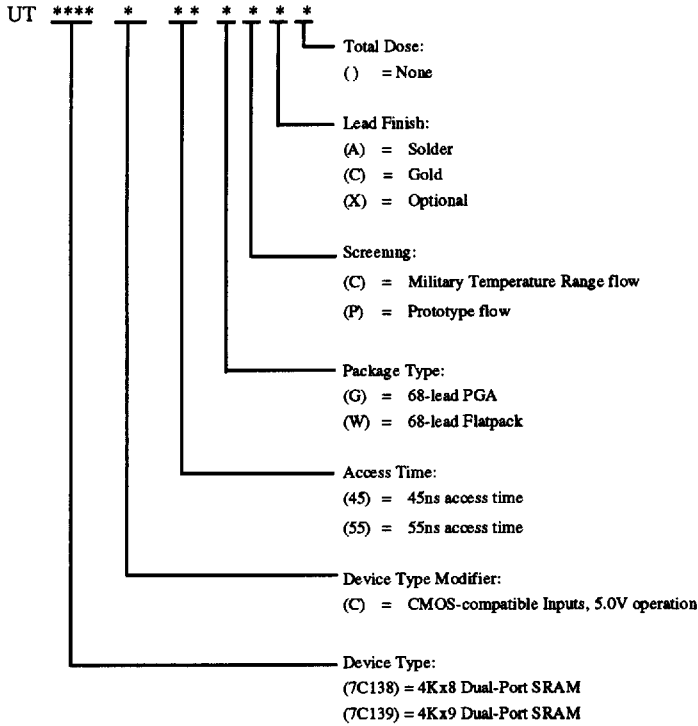
5962 \* 96845 \* \* \* \*



### Notes:

1. Lead finish (A, C, or X) must be specified.
2. If an "X" is specified when ordering, part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
3. Total dose radiation must be specified when ordering. QML Q and QML V not available without radiation hardening.

**UT7C138/UT7C139 Dual-Port SRAM**



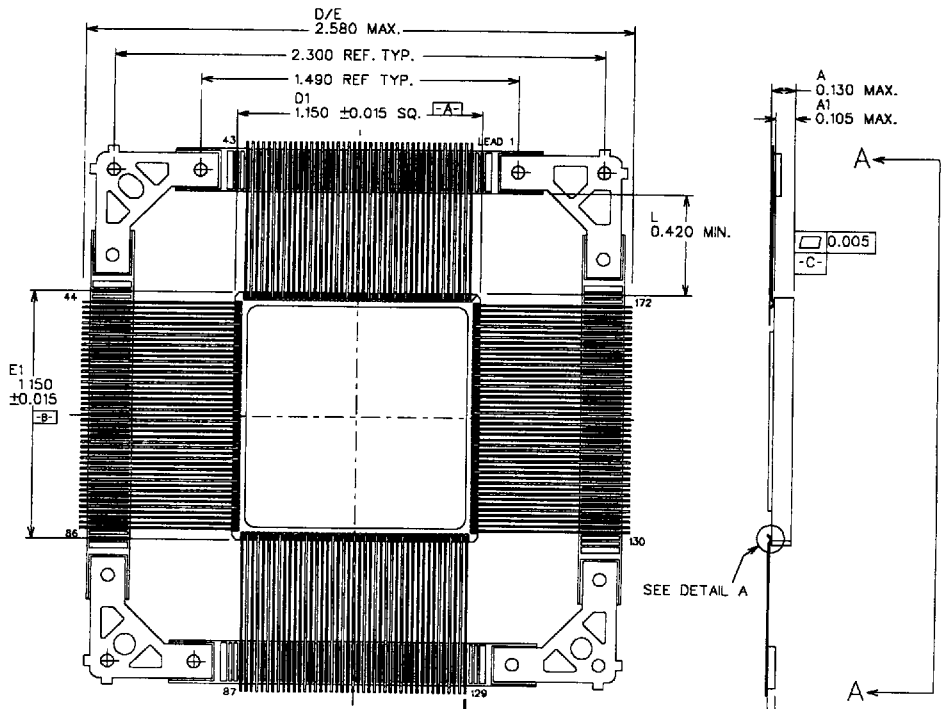
**Notes:**

1. Lead finish (A,C, or X) must be specified.
2. If an "X" is specified when ordering, then the part marking will match the lead finish and will be either "A" (solder) or "C" (gold).
3. Military Temperature Range flow per UTMC Manufacturing Flows Document. Radiation characteristics are neither tested nor guaranteed and may not be specified.
4. Prototype flow per UTMC Manufacturing Flows Document. Devices have prototype assembly and are tested at 25°C only. Radiation characteristics are neither tested nor guaranteed and may not be specified.

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## 11.0 Packages

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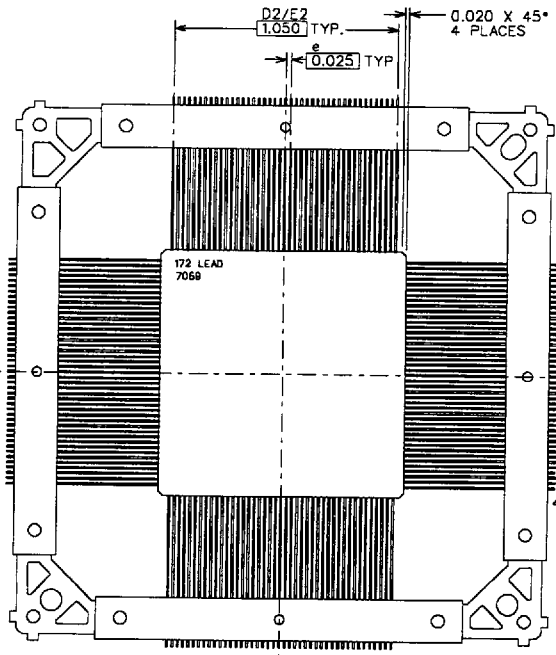


TOP VIEW

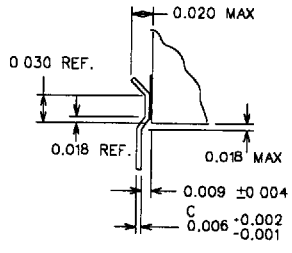
SIDE VIEW

$b$	$0.008^{+0.002}$	$-0.001$	TYP.
$\oplus$	$0.030$	$\text{M}$	$\text{C}$
$\oplus$	$0.007$	$\text{M}$	$\text{C}$

(FULL LENGTH OF LEAD)  
 $0.020 \times 45^\circ$  REF.  
 4 PLACES



VIEW A-A

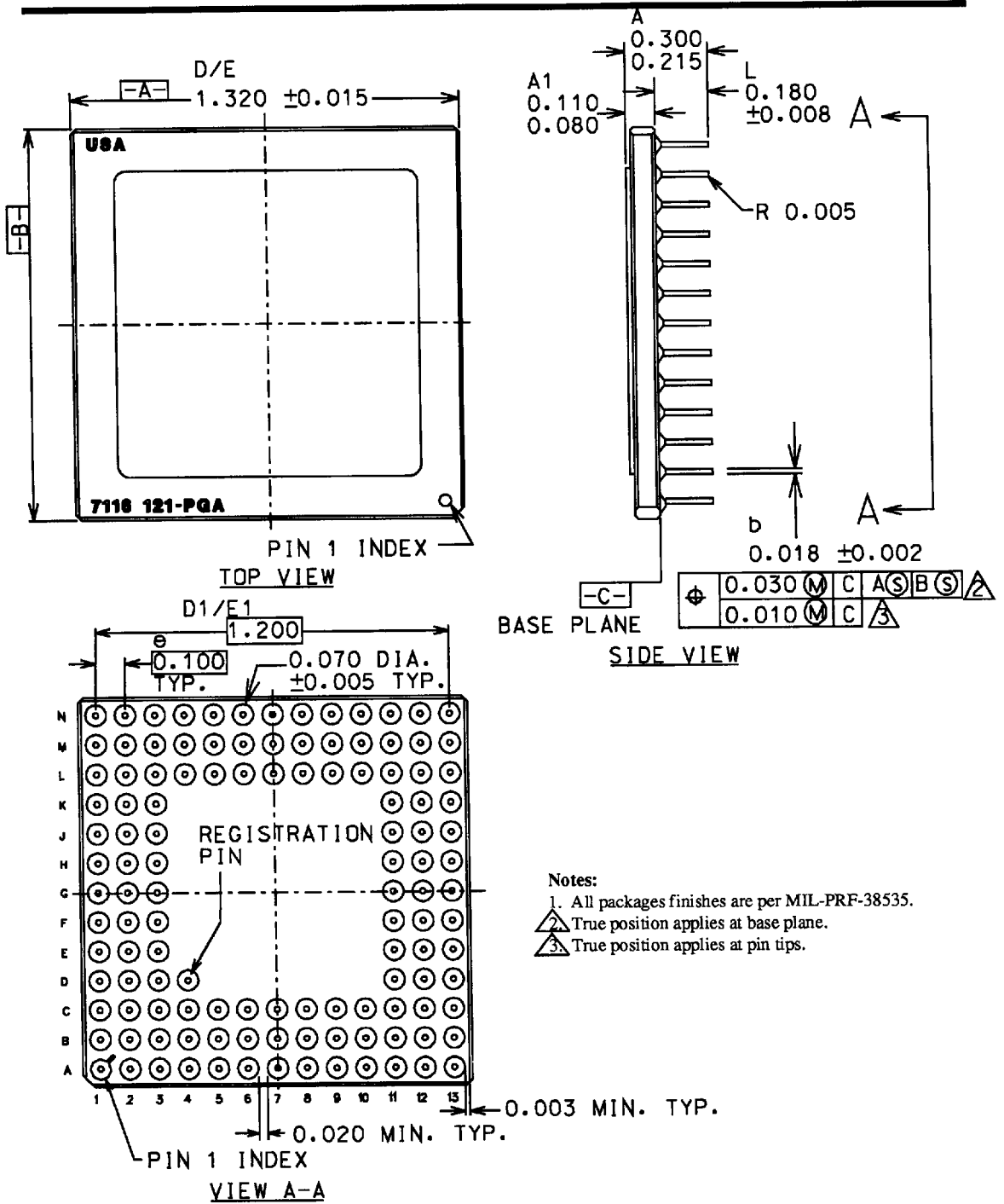


DETAIL A

**Notes:**

1. Lead finish is in accordance with MIL-PRF-38535.
2. Letter designations are for cross-reference to MIL-STD-1835.
3. Lead coplanarity and true position are not measured.

**Figure 11-1. 172-lead flatpack package (UTMC Drawing # 44121)**



- Notes:
- All packages finishes are per MIL-PRF-38535.
  - True position applies at base plane.
  - True position applies at pin tips.

Figure 11-2. 121-pin pingrid array package  
(UTMC Drawing # 44128)